

HM5116100L Series Low Power Version**Product Preview**

T-46-23-15

16,777,216-Word x 1-Bit Dynamic Random Access Memory

DESCRIPTION

The Hitachi HM5116100 is a CMOS dynamic RAM organized 16,777,216 words x 1-bit. It employs the most advanced CMOS technology for high performance and low power. The HM5116100 offers Fast Page Mode as a high speed access mode.

FEATURES

- Single 5V ($\pm 10\%$)
- High Speed
 - Access Time 60 ns/70 ns/80 ns/100 ns (max)
- Low Power Dissipation
 - Active Mode 495 mW/440 mW/385 mW/330 mW (max)
 - Standby Mode 11 mW (max)
- Fast Page Mode Capability
- Long Refresh Period
 - 4096 Refresh Cycles (256 ms)
- 3 Variations of Refresh
 - RAS Only Refresh
 - CAS Before RAS Refresh
 - Hidden Refresh
- Battery Back Up Operation

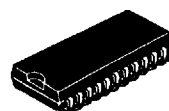
ORDERING INFORMATION

Part No.	Access Time	Package
HM5116100LJ-6	60 ns	400 mil 24-pin Plastic SOJ (CP-24D)
HM5116100LJ-7	70 ns	
HM5116100LJ-8	80 ns	
HM5116100LJ-10	100 ns	
HM5116100LZ-6	60 ns	475 mil 24-pin Plastic ZIP (ZP-24)
HM5116100LZ-7	70 ns	
HM5116100LZ-8	80 ns	
HM5116100LZ-10	100 ns	

PIN DESCRIPTION

Pin Name	Function
A ₀ -A ₁₁	Address Input
A ₀ -A ₁₁	Refresh Address Input
D _{in}	Data Input
D _{out}	Data Output
RAS	Row Address Strobe
CAS	Column Address Strobe
WE	Read/Write Enable
V _{CC}	Power Supply (+ 5V)
V _{SS}	Ground
NC	No Connection

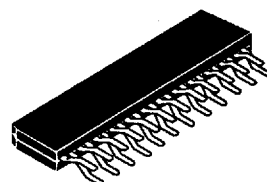
HM5116100LJ Series



(CP-24D)

3DCP24D

HM5116100LZ Series

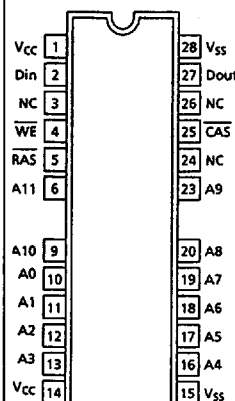


(ZP-24)

3DZP24

PIN OUT

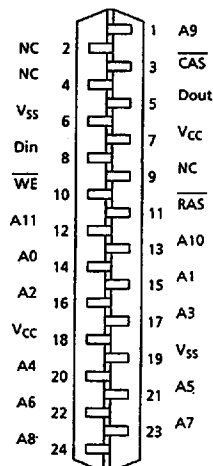
HM5116100LJ Series



(Top View)

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HM5116100LZ Series



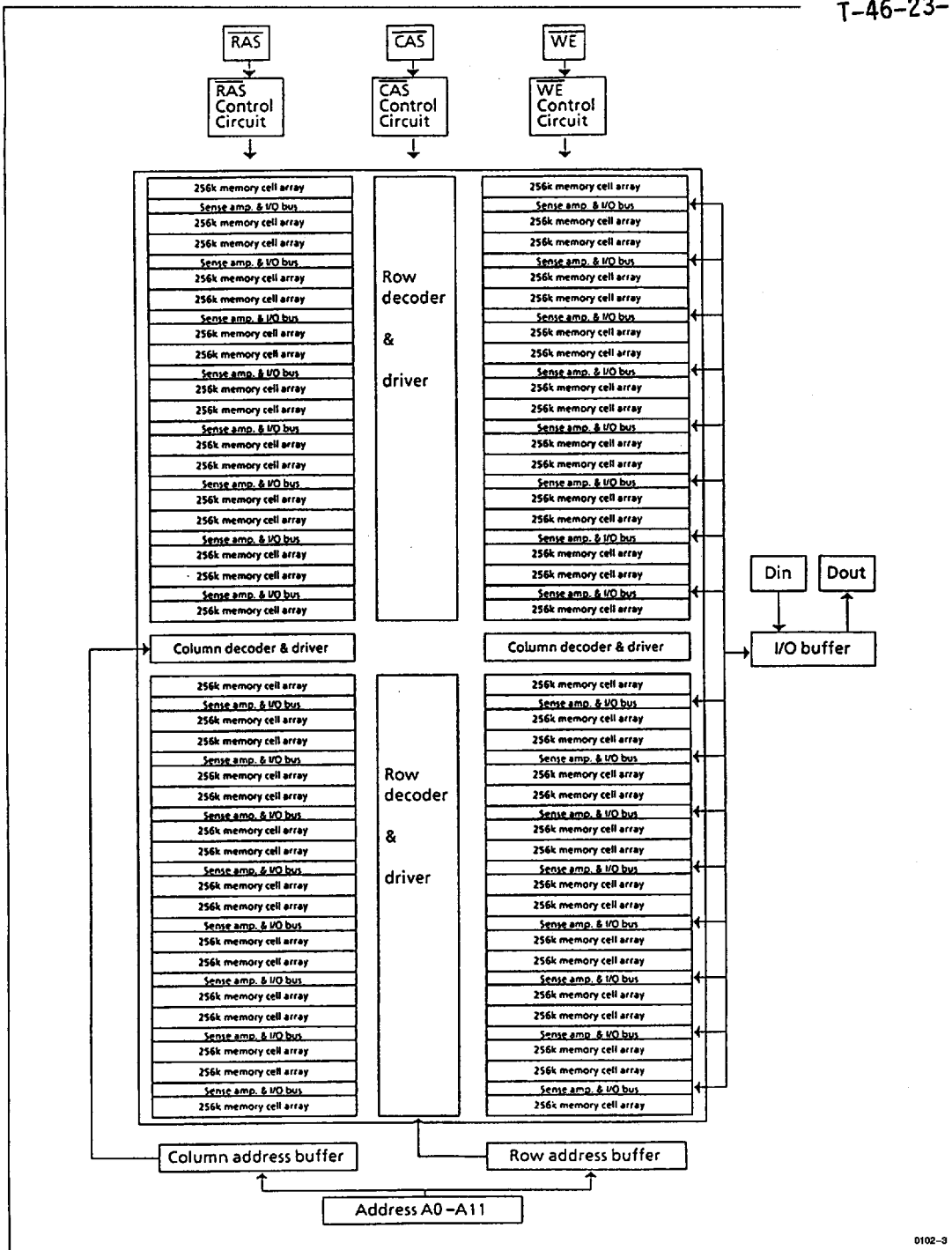
(Bottom View)

0102-2



■ BLOCK DIAGRAM

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0102-3



■ ABSOLUTE MAXIMUM RATINGS

HITACHI/ LOGIC/ARRAYS/MEM

Parameter	Symbol	Value	Unit
Voltage on Any Pin Relative to V_{SS}	V_T	-1.0 to +7.0	V
Supply Voltage Relative to V_{SS}	V_{CC}	-1.0 to +7.0	V
Short Circuit Output Current	I_{out}	50	mA
Power Dissipation	P_T	1.0	W
Operating Temperature	T_{opr}	0 to +70	°C
Storage Temperature	T_{stg}	-55 to +125	°C

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■ ELECTRICAL CHARACTERISTICS

• Recommended DC Operating Conditions ($T_A = 0$ to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply Voltage	V_{CC}	4.5	5.0	5.5	V	1
Input High Voltage	V_{IH}	2.4	—	6.5	V	1
Input Low Voltage	V_{IL}	-1.0	—	0.8	V	1

Note: 1. All voltage referenced to V_{SS} .• DC Electrical Characteristics ($T_A = 0$ to +70°C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$)

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Test Condition	Note
		Min	Max	Min	Max	Min	Max	Min	Max			
Operating Current	I_{CC1}	—	90	—	80	—	70	—	60	mA	$t_{RC} = \text{Min}$	1, 2
Standby Current	I_{CC2}	—	2	—	2	—	2	—	2	mA	TTL Interface RAS, CAS = V_{IH} $D_{out} = \text{High-Z}$	
		—	300	—	300	—	300	—	300	μA	CMOS Interface RAS, CAS and $\overline{WE} > V_{CC} - 0.2V$, or $\leq 6.5V$ Address and $D_{in} = \text{Stable}$ $D_{out} = \text{High-Z}$	
RAS Only Refresh Current	I_{CC3}	—	90	—	80	—	70	—	60	mA	$t_{RC} = \text{Min}$	2
Standby Current	I_{CC5}	—	5	—	5	—	5	—	5	mA	RAS = V_{IH} CAS = V_{IL} $D_{out} = \text{Enable}$	1, 4
CAS Before RAS Refresh Current	I_{CC6}	—	90	—	80	—	70	—	60	mA	$t_{RC} = \text{Min}$	4
Fast Page Mode Current	I_{CC7}	—	70	—	60	—	50	—	45	mA	$t_{PC} = \text{Min}$	1, 3
Battery Back-up Operating Current (Standby with CBR Refresh)	I_{CC10}	—	500	—	500	—	500	—	500	μA	Standby: CMOS Interface CBR Refresh: $t_{RC} = 62.5 \mu s$ $t_{RAS} \leq 1 \mu s$ Address and $D_{in} = \text{Stable}$ $D_{out} = \text{High-Z}$	5
Input Leakage Current	I_{LI}	-10	10	-10	10	-10	10	-10	10	μA	$0V \leq V_{in} \leq 7V$	
Output Leakage Current	I_{LO}	-10	10	-10	10	-10	10	-10	10	μA	$0V \leq V_{out} \leq 7V$ $D_{out} = \text{Disable}$	



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• DC Electrical Characteristics ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$) (continued)

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Test Condition	Note
		Min	Max	Min	Max	Min	Max	Min	Max			
Output High Voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	High $I_{out} = -5\text{mA}$	
Output Low Voltage	V_{OL}	0	0.4	0	0.4	0	0.4	0	0.4	V	Low $I_{out} = 4.2\text{mA}$	

Notes: 1. I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.3. Address can be changed once or less while $\overline{CAS} = V_{IH}$.4. Clock voltages ($\overline{RAS}$ and $\overline{CAS}$) must be applied simultaneously with or prior to applying supply voltage.5. $V_{CC} - 0.2\text{V} \leq V_{IH} \leq 6.5\text{V}$, $0\text{V} \leq V_{IL} \leq 0.2\text{V}$.• Capacitance ($T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 10\%$)

HITACHI/ LOGIC/ARRAYS/MEM

Parameter	Symbol	Typ	Max	Unit	Note
Input Capacitance (Address, Data-in)	C_{I1}	—	5	pF	1
Input Capacitance (Clocks)	C_{I2}	—	7	pF	1
Output Capacitance (Data-out)	C_O	—	7	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{CAS} = V_{IH}$ to disable D_{out} .• AC Characteristics ($T_A = 0$ to 70°C , $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$)^{1, 2, 16}

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Max	Max		
Random Read or Write Cycle Time	t_{RC}	110	—	130	—	150	—	180	—	ns	
$\overline{RAS}$ Precharge Time	t_{RP}	40	—	50	—	60	—	70	—	ns	
$\overline{CAS}$ Precharge Time	t_{CP}	10	—	10	—	10	—	10	—	ns	
$\overline{RAS}$ Pulse Width	t_{RAS}	60	10000	70	10000	80	10000	100	10000	ns	
$\overline{CAS}$ Pulse Width	t_{CAS}	15	10000	18	10000	20	10000	25	10000	ns	
Row Address Setup Time	t_{ASR}	0	—	0	—	0	—	0	—	ns	
Row Address Hold Time	t_{RAH}	10	—	10	—	10	—	10	—	ns	
Column Address Setup Time	t_{ASC}	0	—	0	—	0	—	0	—	ns	
Column Address Hold Time	t_{CAH}	15	—	15	—	15	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ Delay Time	t_{RCD}	20	45	20	52	20	60	20	75	ns	3
$\overline{RAS}$ to Column Address Delay Time	t_{RAD}	15	30	15	35	15	40	15	55	ns	4
$\overline{RAS}$ Hold Time	t_{RSH}	15	—	18	—	20	—	25	—	ns	
$\overline{CAS}$ Hold Time	t_{CSH}	60	—	70	—	80	—	100	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	t_{CRP}	5	—	5	—	5	—	5	—	ns	
Transition Time (Rise and Fall)	t_T	3	30	3	30	3	30	3	30	ns	5

Read Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Access Time from $\overline{RAS}$	t_{RAC}	—	60	—	70	—	80	—	100	ns	6, 7, 17
Access Time from $\overline{CAS}$	t_{CAC}	—	15	—	18	—	20	—	25	ns	7, 8, 17
Access Time from Address	t_{AA}	—	30	—	35	—	40	—	45	ns	7, 9, 17
Read Command Setup Time	t_{RCS}	0	—	0	—	0	—	0	—	ns	
Read Command Hold Time to $\overline{CAS}$	t_{RCH}	0	—	0	—	0	—	0	—	ns	10
Read Command Hold Time to $\overline{RAS}$	t_{RRH}	5	—	5	—	5	—	5	—	ns	10



Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Column Address to RAS Lead Time	t _{RAL}	30	—	35	—	40	—	45	—	ns	
Column Address to CAS Lead Time	t _{CAL}	30	—	35	—	40	—	45	—	ns	
CAS to Output in Low-Z	t _{CLZ}	0	—	0	—	0	—	0	—	ns	
Output Data Hold Time	t _{OH}	3	—	3	—	3	—	3	—	ns	
Output Buffer Turn-off Time	t _{OFF}	—	15	—	18	—	20	—	25	ns	11

Write Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Write Command Setup Time	t _{WCS}	0	—	0	—	0	—	0	—	ns	12
Write Command Hold Time	t _{WCH}	15	—	15	—	15	—	15	—	ns	
Write Command Pulse Width	t _{WP}	15	—	15	—	15	—	15	—	ns	
Write Command to RAS Lead Time	t _{RWL}	15	—	18	—	20	—	25	—	ns	
Write Command to CAS Lead Time	t _{CWL}	15	—	18	—	20	—	25	—	ns	
Data-in Setup Time	t _{DS}	0	—	0	—	0	—	0	—	ns	13
Data-in Hold Time	t _{DH}	15	—	15	—	15	—	15	—	ns	13

Read-Modify-Write Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Read-Modify-Write Cycle Time	t _{RWC}	130	—	153	—	175	—	210	—	ns	
RAS to WE Delay Time	t _{RWD}	60	—	70	—	80	—	100	—	ns	12
CAS to WE Delay Time	t _{CWD}	15	—	18	—	20	—	25	—	ns	12
Column Address to WE Delay Time	t _{AWD}	30	—	35	—	40	—	45	—	ns	12

Refresh Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
CAS Setup Time (CBR Refresh Cycle)	t _{CSR}	10	—	10	—	10	—	10	—	ns	
CAS Hold Time (CBR Refresh Cycle)	t _{CHR}	20	—	20	—	20	—	20	—	ns	
WE Setup Time (CBR Refresh Cycle)	t _{WRP}	10	—	10	—	10	—	10	—	ns	
WE Hold Time (CBR Refresh Cycle)	t _{WRH}	10	—	10	—	10	—	10	—	ns	
RAS Precharge to CAS Hold Time	t _{RPC}	0	—	0	—	0	—	0	—	ns	

Fast Page Mode Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Fast Page Mode Cycle Time	t _{PC}	40	—	45	—	50	—	55	—	ns	
Fast Page Mode RAS Pulse Width	t _{RASP}	—	100000	—	100000	—	100000	—	100000	ns	14
Access Time from CAS Precharge	t _{CPA}	—	35	—	40	—	45	—	50	ns	15, 17
WE Delay Time from CAS Precharge	t _{CPW}	35	—	40	—	45	—	50	—	ns	
RAS Hold Time from CAS Precharge	t _{CPRH}	35	—	40	—	45	—	50	—	ns	



Fast Page Mode Read-Modify-Write Cycle

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Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Fast Page Mode Read-Modify-Write Cycle Time	t _{PRWC}	60	—	68	—	75	—	85	—	ns	

Test Mode Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
Test Mode $\overline{WE}$ Setup Time	t _{WTS}	10	—	10	—	10	—	10	—	ns	
Test Mode $\overline{WE}$ Hold Time	t _{WTH}	10	—	10	—	10	—	10	—	ns	

Counter Test Cycle

Parameter	Symbol	HM5116100-6		HM5116100-7		HM5116100-8		HM5116100-10		Unit	Note
		Min	Max	Min	Max	Min	Max	Min	Max		
$\overline{CAS}$ Precharge Time in Counter Test Cycle	t _{CPT}	TBD	—	TBD	—	TBD	—	TBD	—	ns	

Refresh ($T_J = 85^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$)

Parameter	Symbol	Max	Unit	Note
Refresh Period	t _{REF}	256	ms	4096 Cycles

- Notes:
1. AC measurements assume $t_T = 5$ ns.
 2. An initial pause of 100 μs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$ only refresh or $\overline{CAS}$ before $\overline{RAS}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$ before $\overline{RAS}$ refresh cycles are required.
 3. Operation with the $t_{RCD}(\text{max})$ limit insures that $t_{RAC}(\text{max})$ can be met, $t_{RCD}(\text{max})$ is specified as a reference point only; if t_{RCD} is greater than the specified $t_{RCD}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
 4. Operation with the $t_{RAD}(\text{max})$ limit insures that $t_{RAC}(\text{max})$ can be met, $t_{RAD}(\text{max})$ is specified as a reference point only; if t_{RAD} is greater than the specified $t_{RAD}(\text{max})$ limit, then access time is controlled exclusively by t_{AA} .
 5. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing of input signals. Also, transition times are measured between $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$.
 6. Assumes that $t_{RCD} < t_{RCD}(\text{max})$ and $t_{RAD} < t_{RAD}(\text{max})$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 7. Measured with a load circuit equivalent to 2TTL loads and 100 pF.
 8. Assumes that $t_{RCD} \geq t_{RCD}(\text{max})$ and $t_{RAD} \leq t_{RAD}(\text{max})$.
 9. Assumes that $t_{RCD} \leq t_{RCD}(\text{max})$ and $t_{RAD} \geq t_{RAD}(\text{max})$.
 10. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
 11. $t_{OFF}(\text{max})$ defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
 12. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}(\text{min})$, the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}(\text{min})$, $t_{CWD} \geq t_{CWD}(\text{min})$ and $t_{AWD} \geq t_{AWD}(\text{min})$, or $t_{CWD} \geq t_{CWD}(\text{min})$, $t_{AWD} \geq t_{AWD}(\text{min})$, and $t_{CPW} \geq t_{CPW}(\text{min})$, the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
 13. These parameters are referenced to $\overline{CAS}$ leading edge in early write cycles and to $\overline{WE}$ leading edge in delayed write or read-modify-write cycles.
 14. t_{RASP} defines $\overline{RAS}$ pulse width in fast page mode cycles.
 15. Access time is determined by the longer of t_{AA} or t_{CAC} or t_{CPA} .
 16. Test mode operation specified in this data sheet is 16 bits test function controlled by compression addresses — CA0, CA1, CA10 and CA11. This test mode operation can be performed by $\overline{WE}$ and $\overline{CAS}$ before $\overline{RAS}$ (WCBR) refresh cycle. Refresh during test mode operation will be performed by normal read cycles or by WCBR refresh cycles. When the state of sixteen test bits accord with each other, the state of the output data is high level. When the state of test bits do not accord with each other, the state of the output data is low level. Data output pin is D_{out} and data input pin is D_{in} . If any refresh cycle is occurred, the test mode is reset.
 17. In a test mode read cycle, the value of t_{RAC} , t_{AA} , t_{CAC} and t_{CPA} is delayed by 2 ns to 5 ns for the specified value. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.

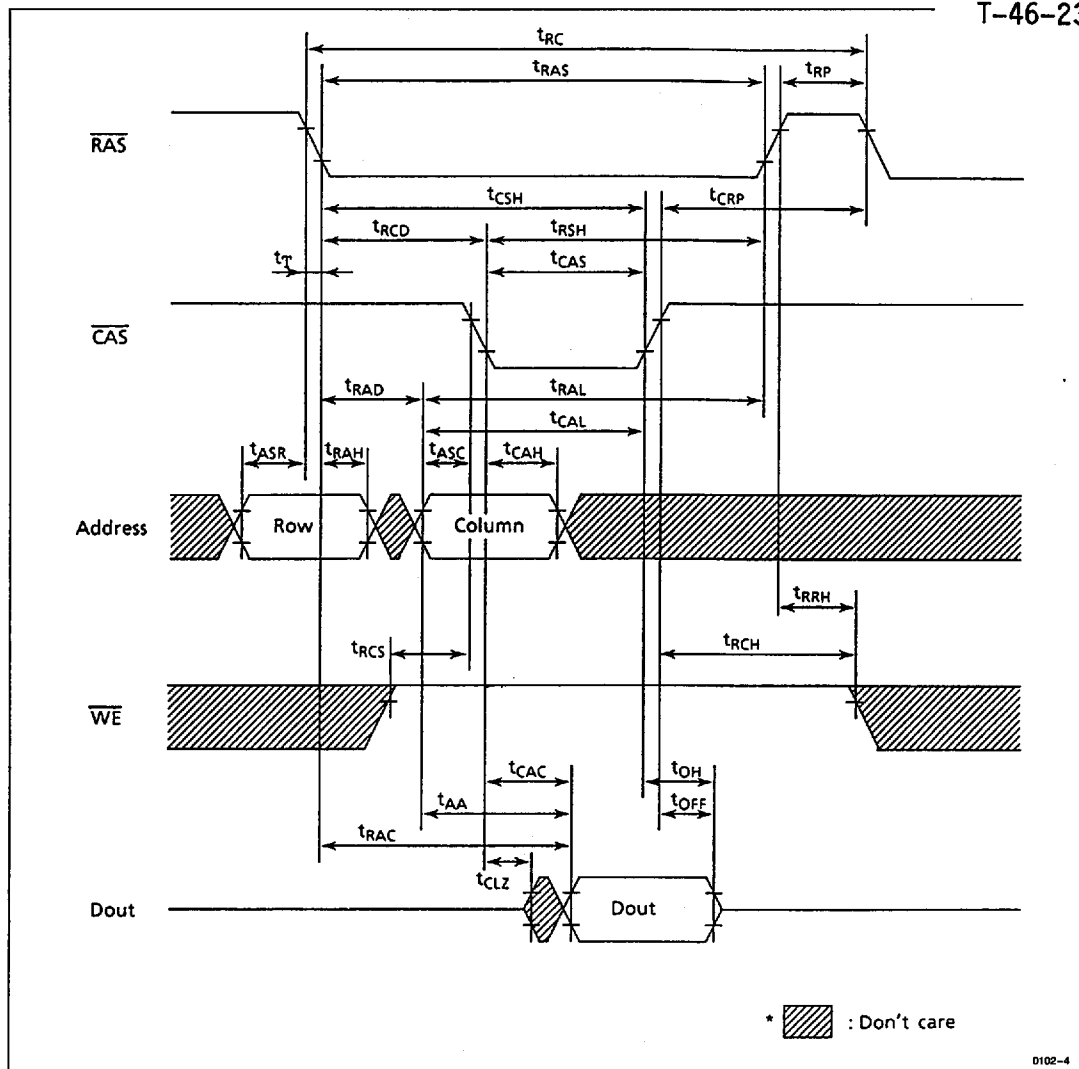


■ TIMING WAVEFORMS

• Read Cycle

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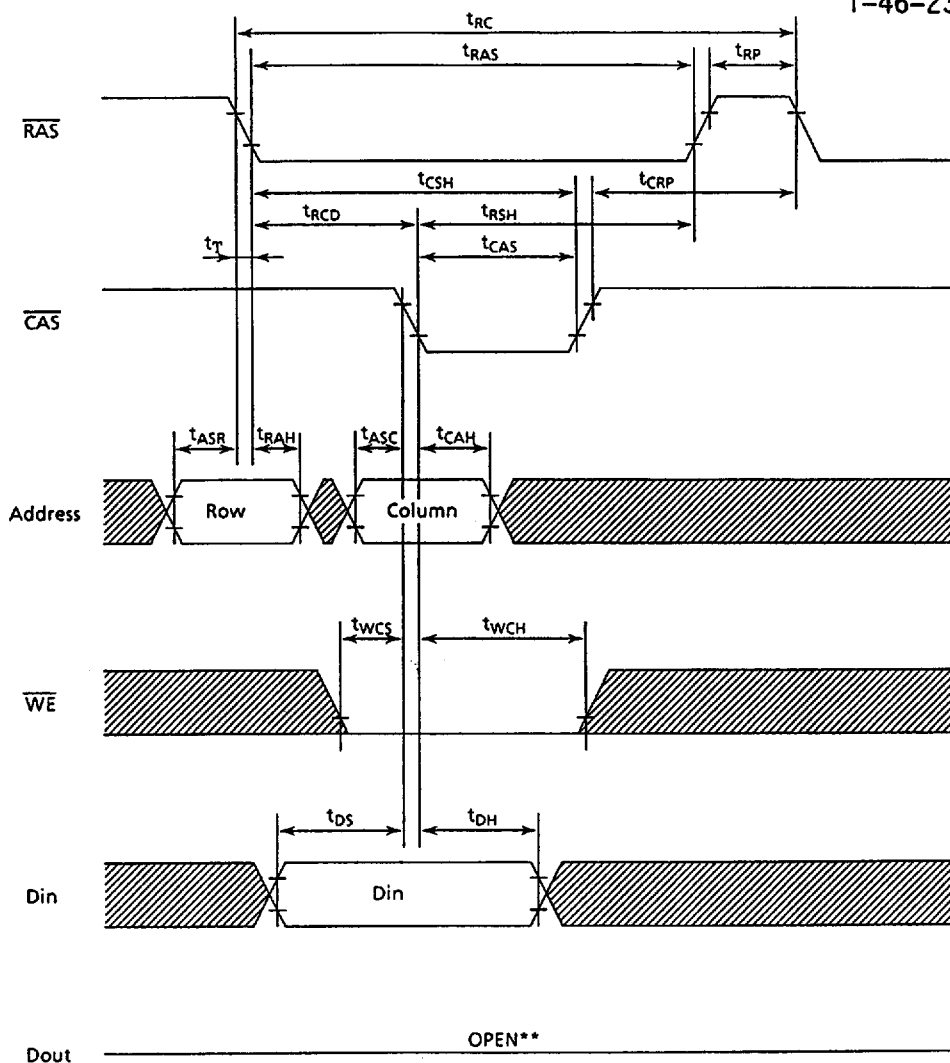
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• Early Write Cycle

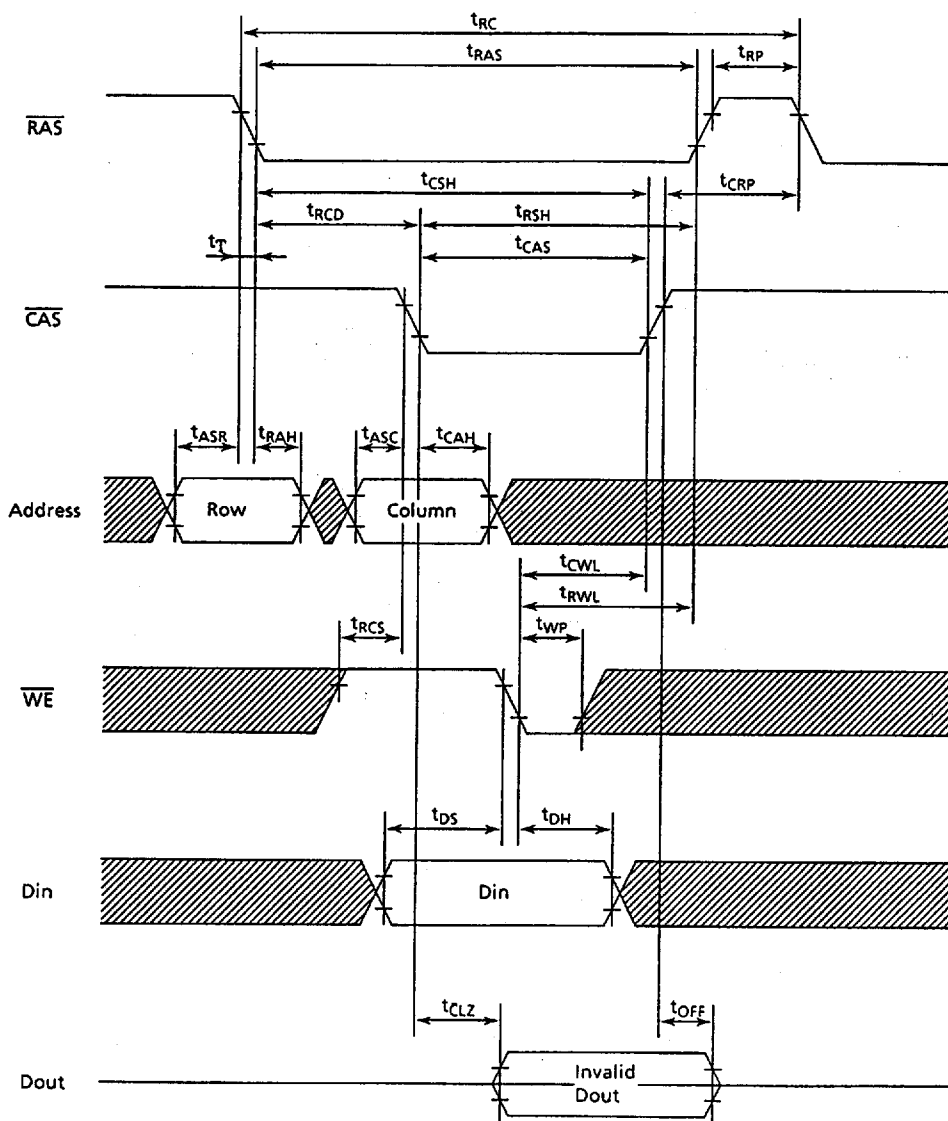
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0102-5





*  : Don't care

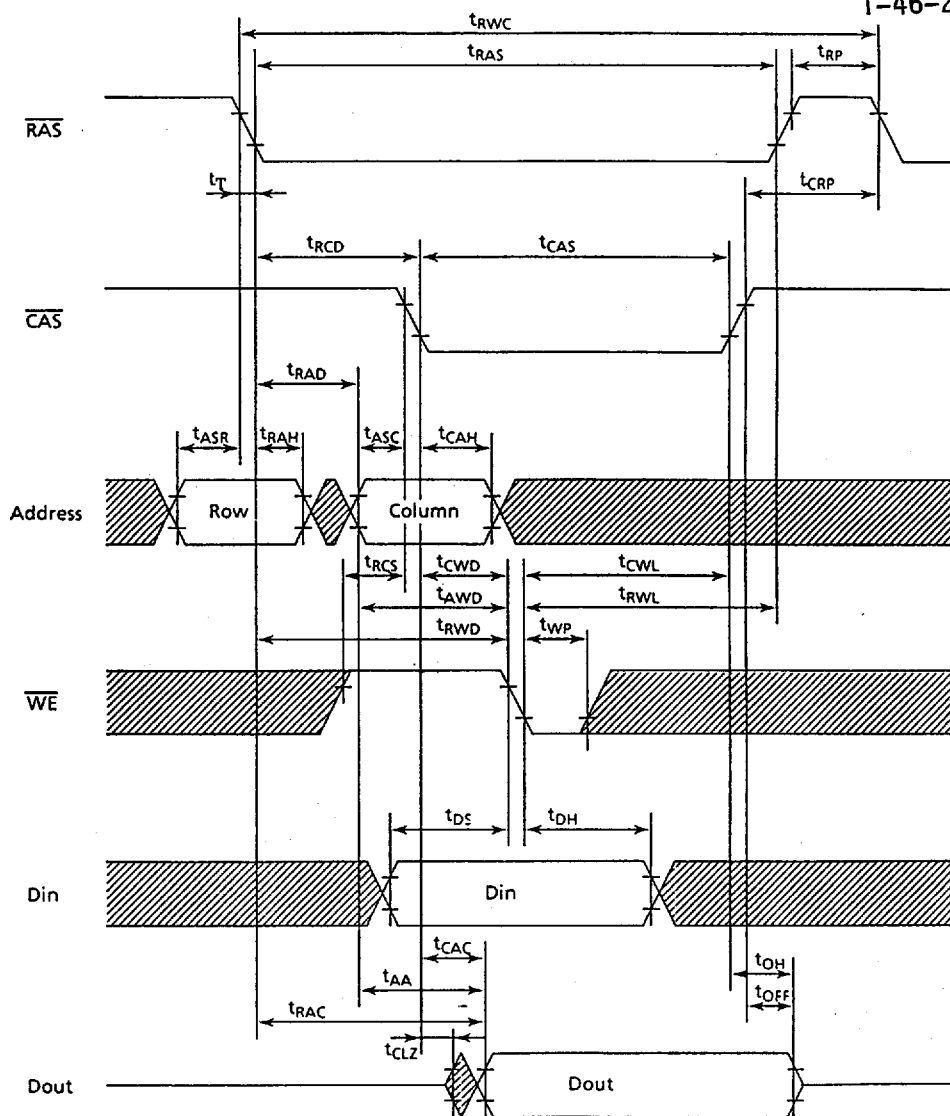
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• Read-Modify-Write Cycle

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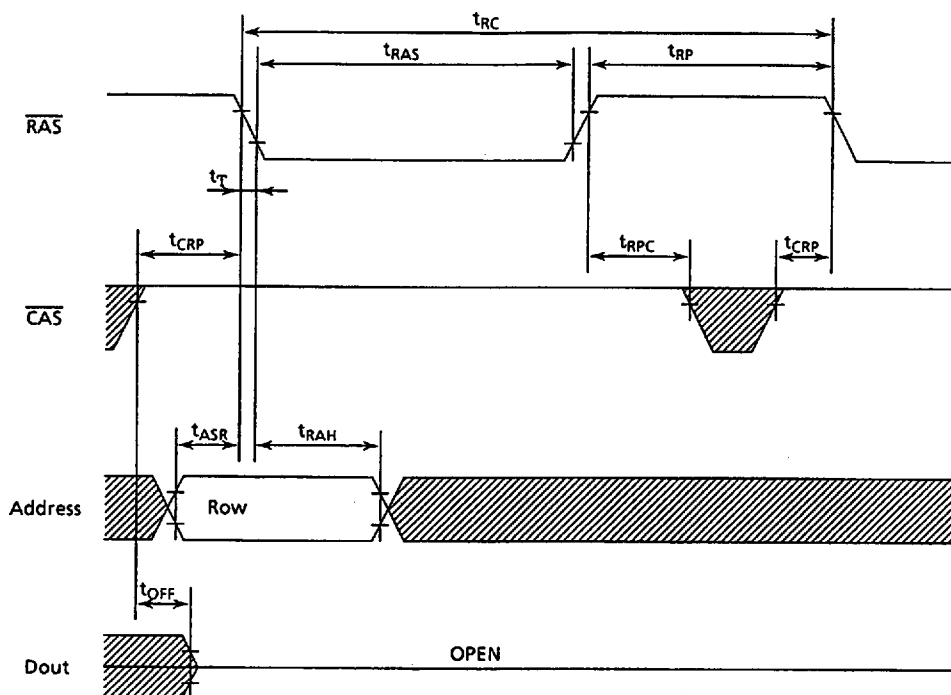
*  : Don't care

0102-7



• RAS Only Refresh Cycle

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* $\overline{\text{WE}}$: Don't care**  : Don't care

*** Refresh address : A0 - A11 (RA0 - RA11)

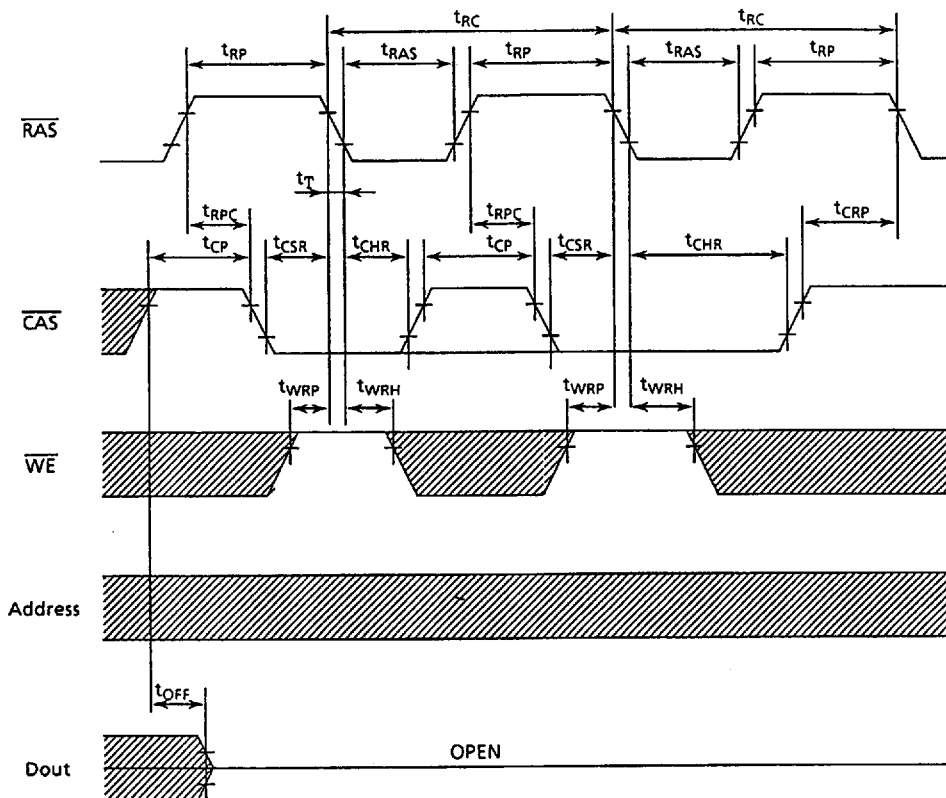
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• $\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Refresh Cycle

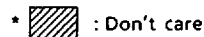
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*  : Don't care

0102-9



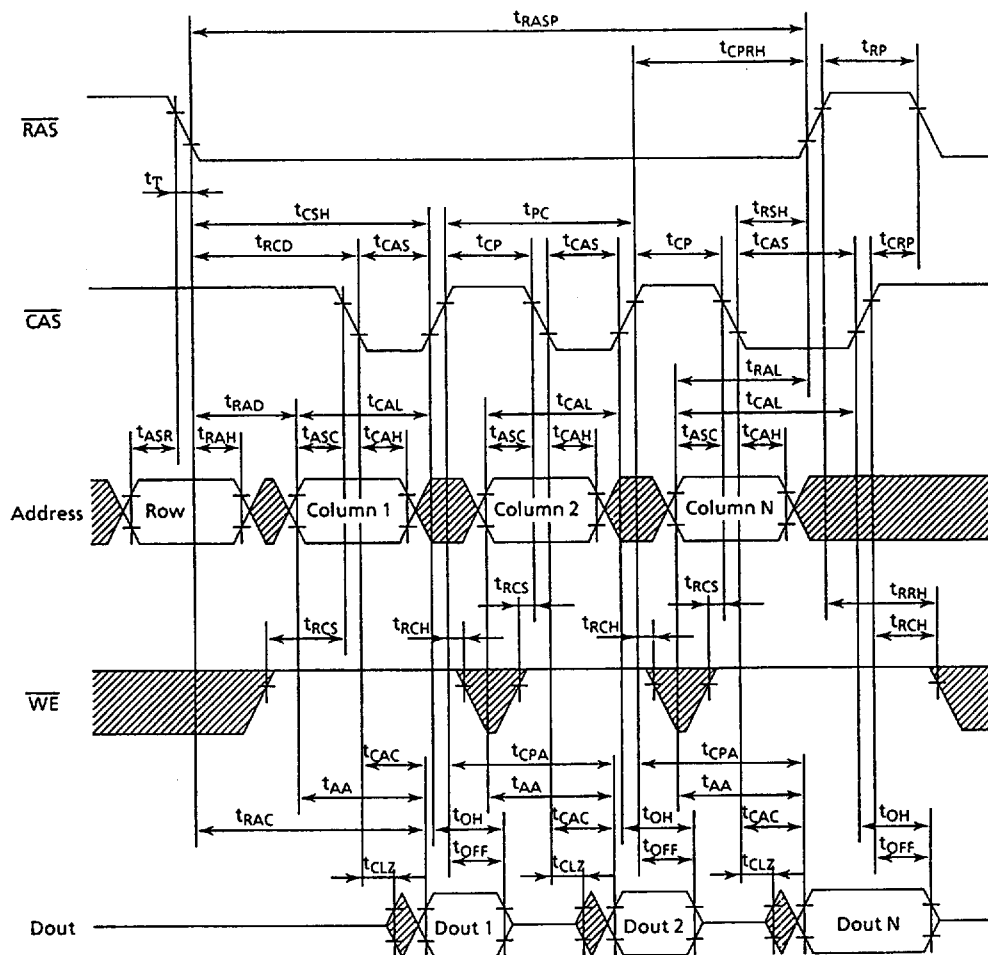


0102-10

• Fast Page Mode Read Cycle

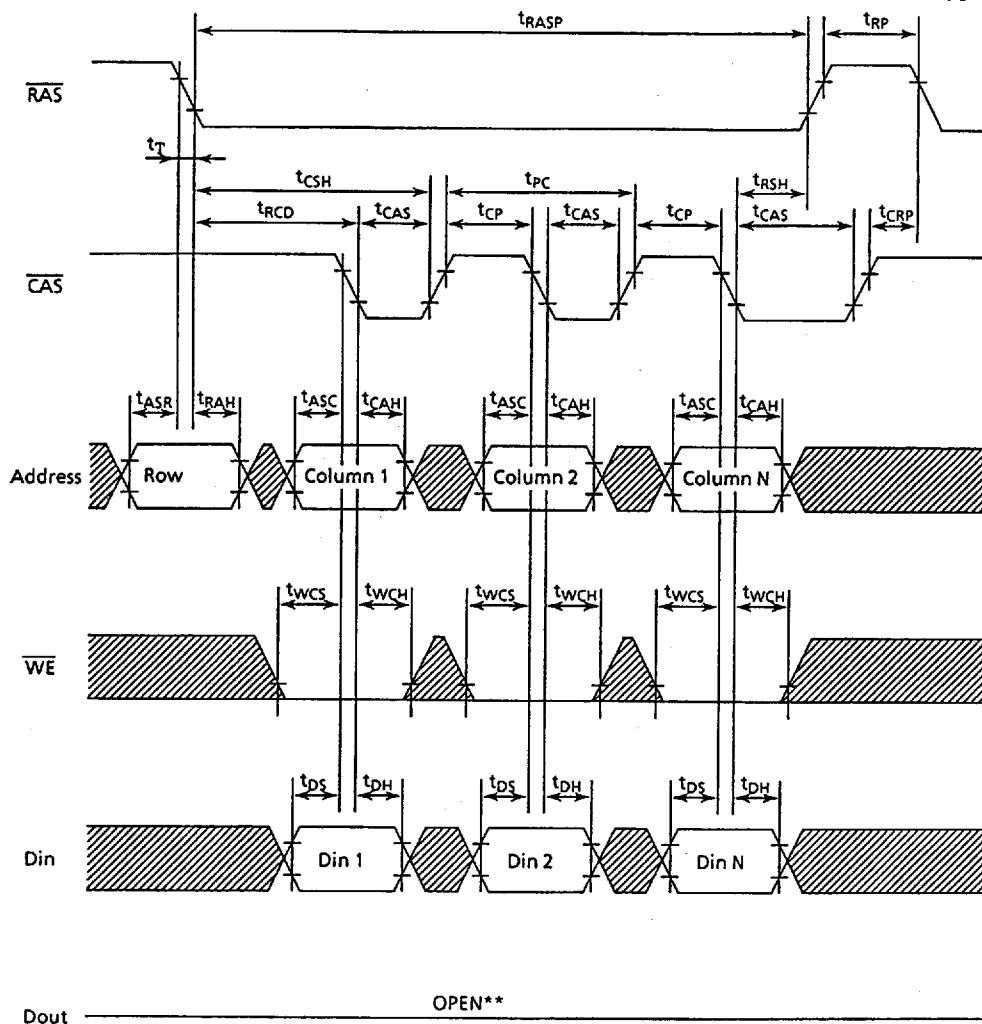
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*  : Don't care

0102-11



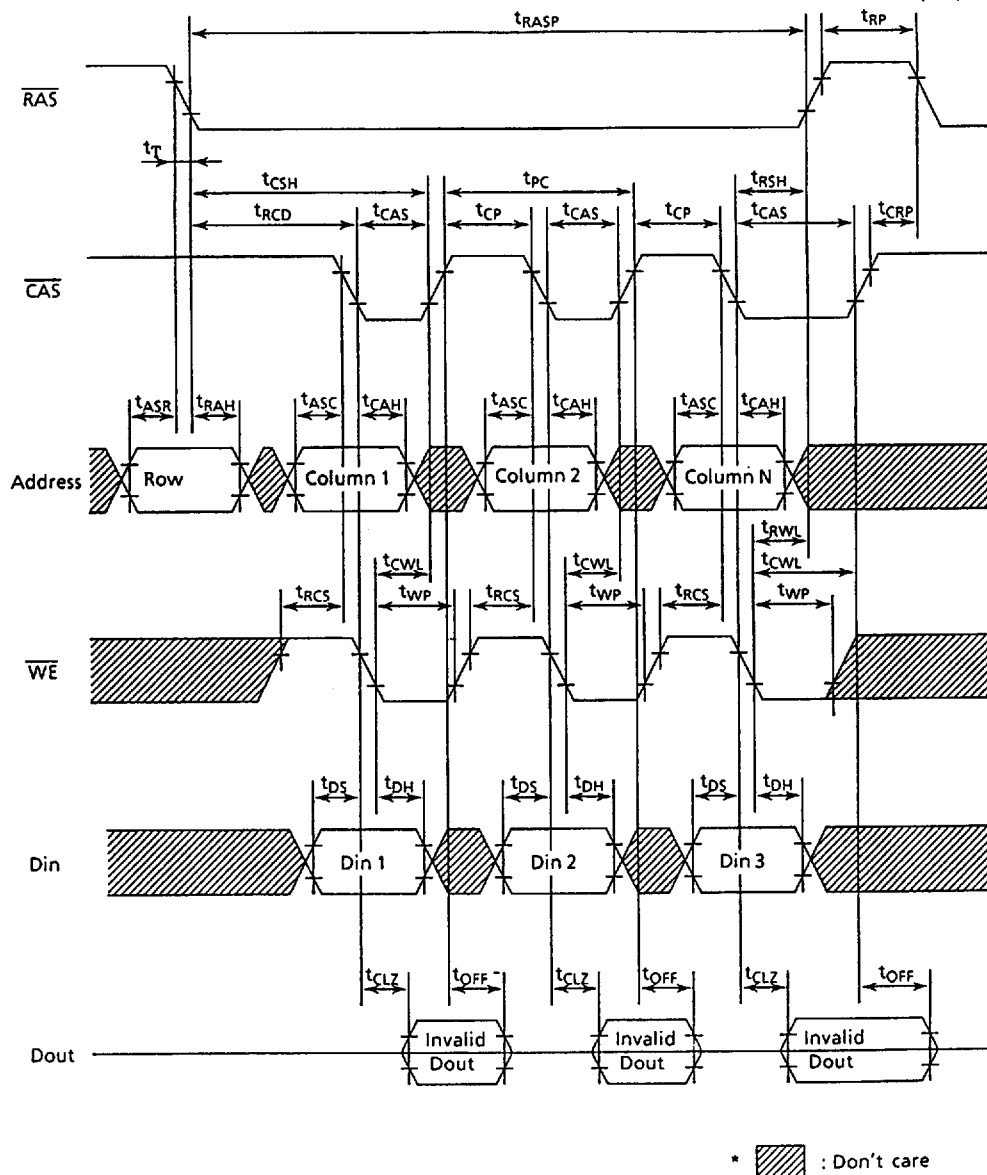


*  : Don't care

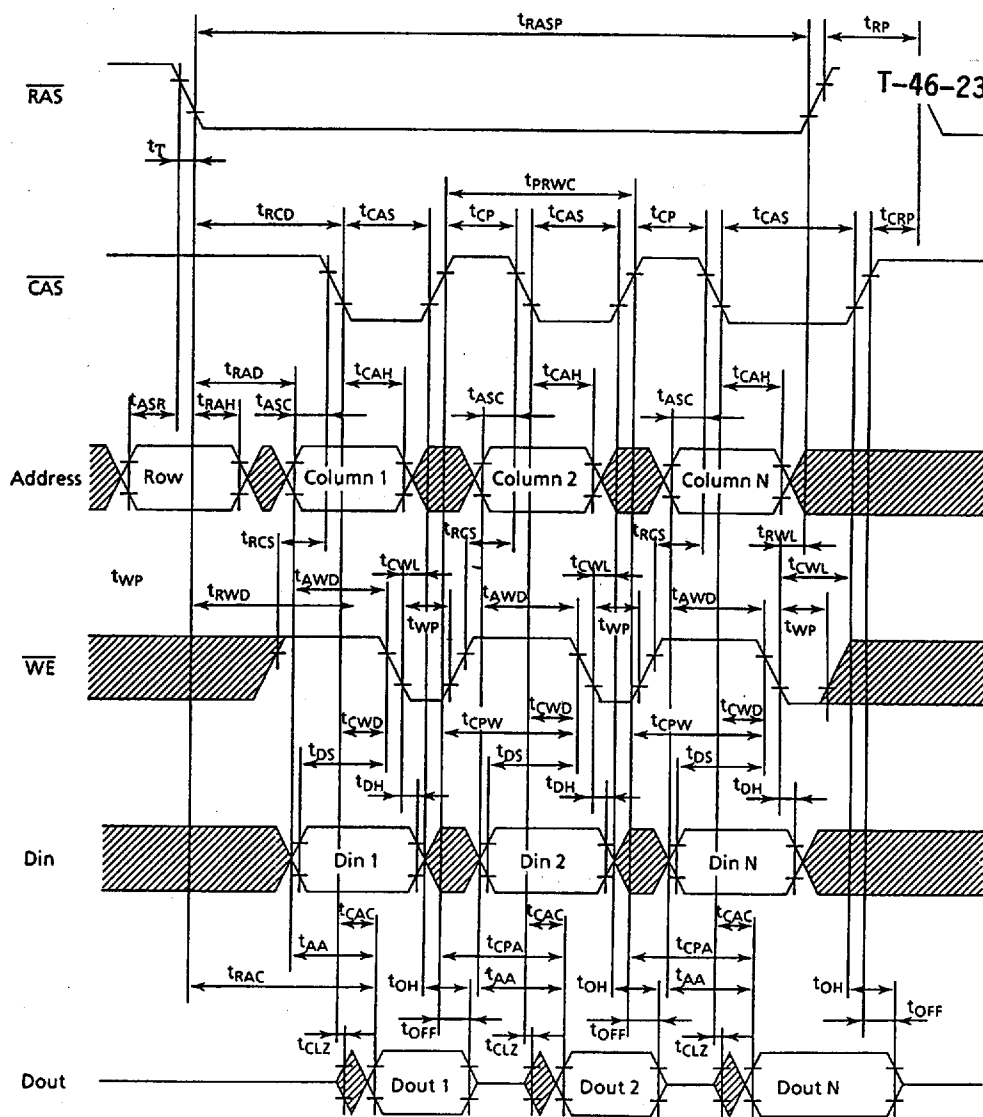
** $t_{WCS} \geq t_{WCS}(\text{min})$

0102-12





0102-13



* : Don't care

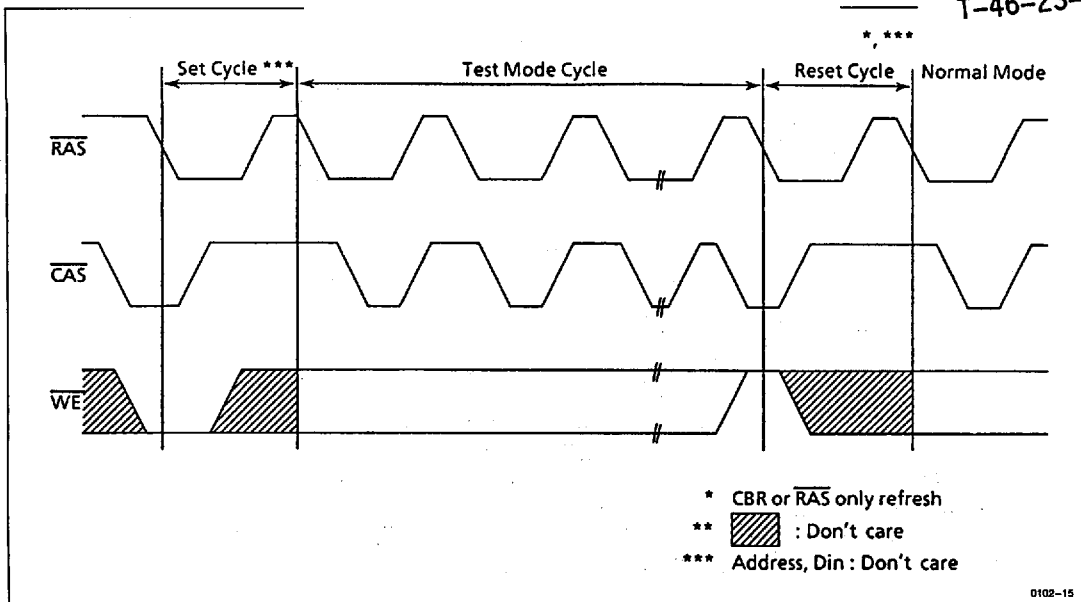
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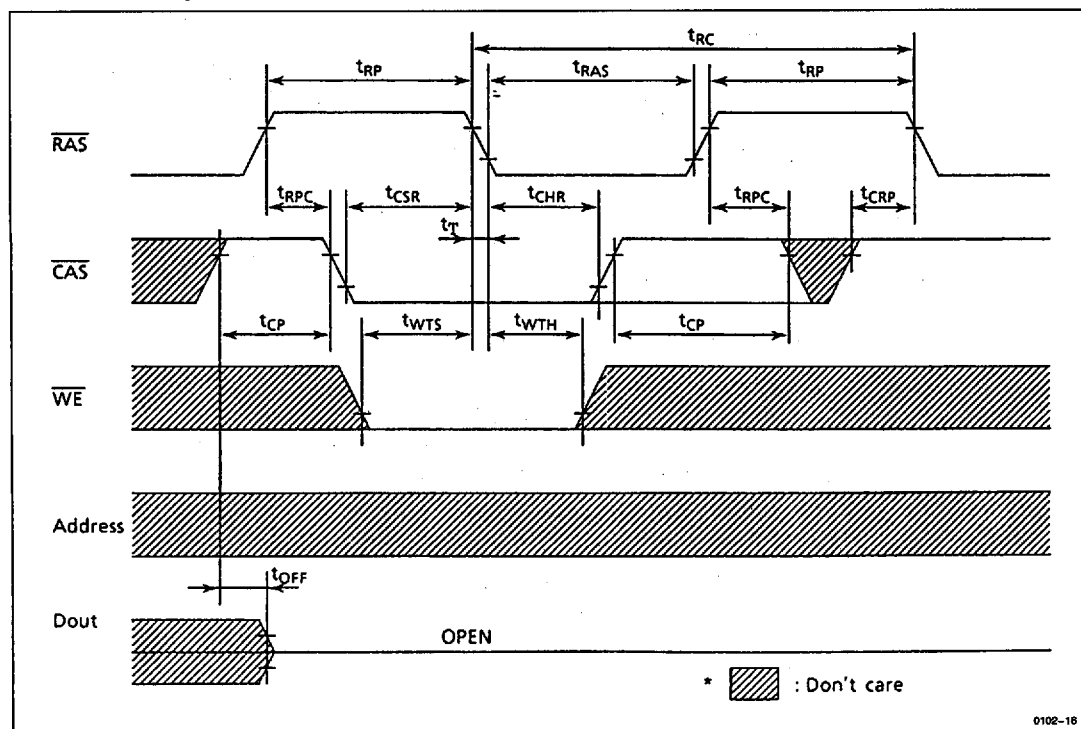
• Test Mode Cycle

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• Test Mode Set Cycle

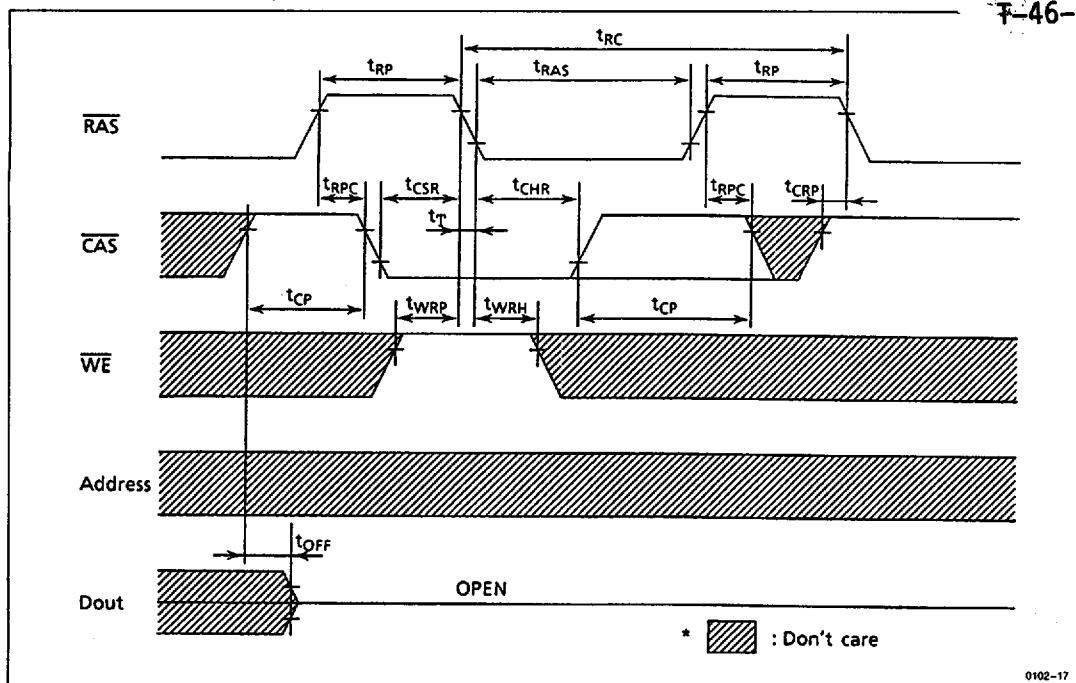


• Test Mode Reset Cycle

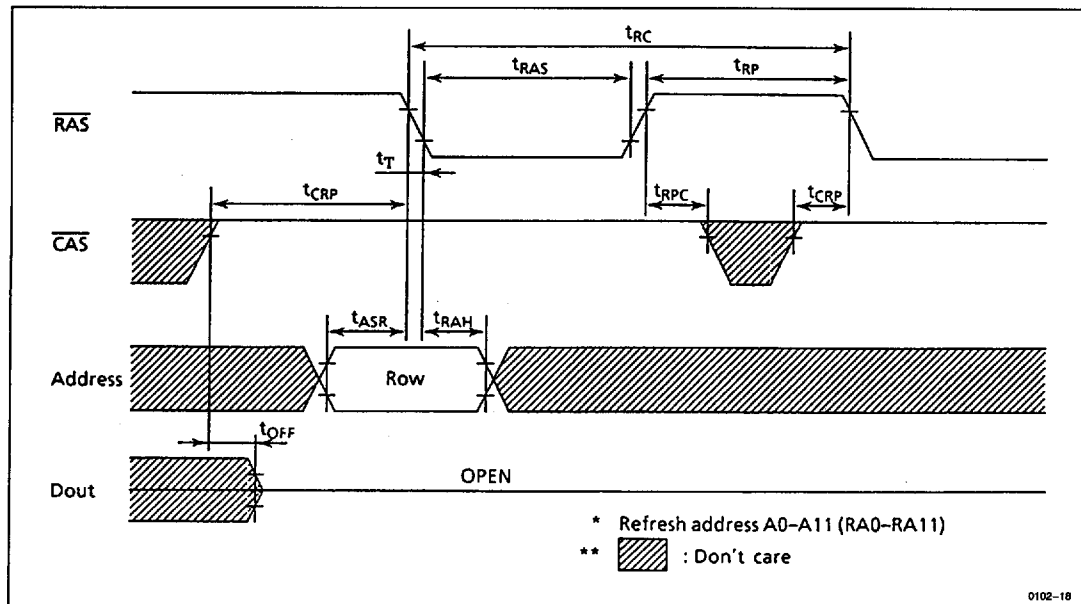
CAS Before RAS Refresh Cycle

HITACHI/ LOGIC/ARRAYS/MEM

T-46-23-15



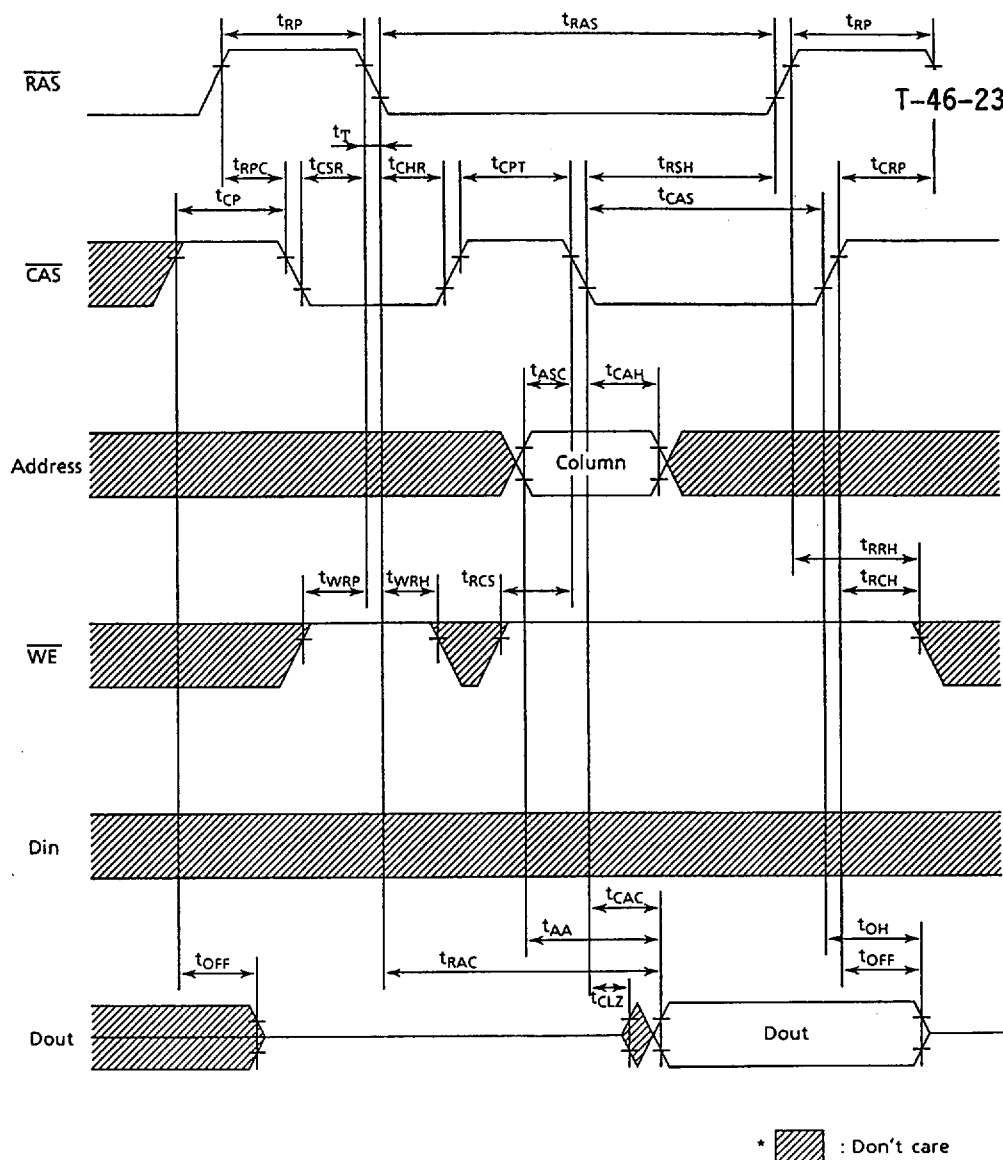
RAS Only Refresh Cycle



CAS Before RAS Refresh Counter Check Cycle (Read)

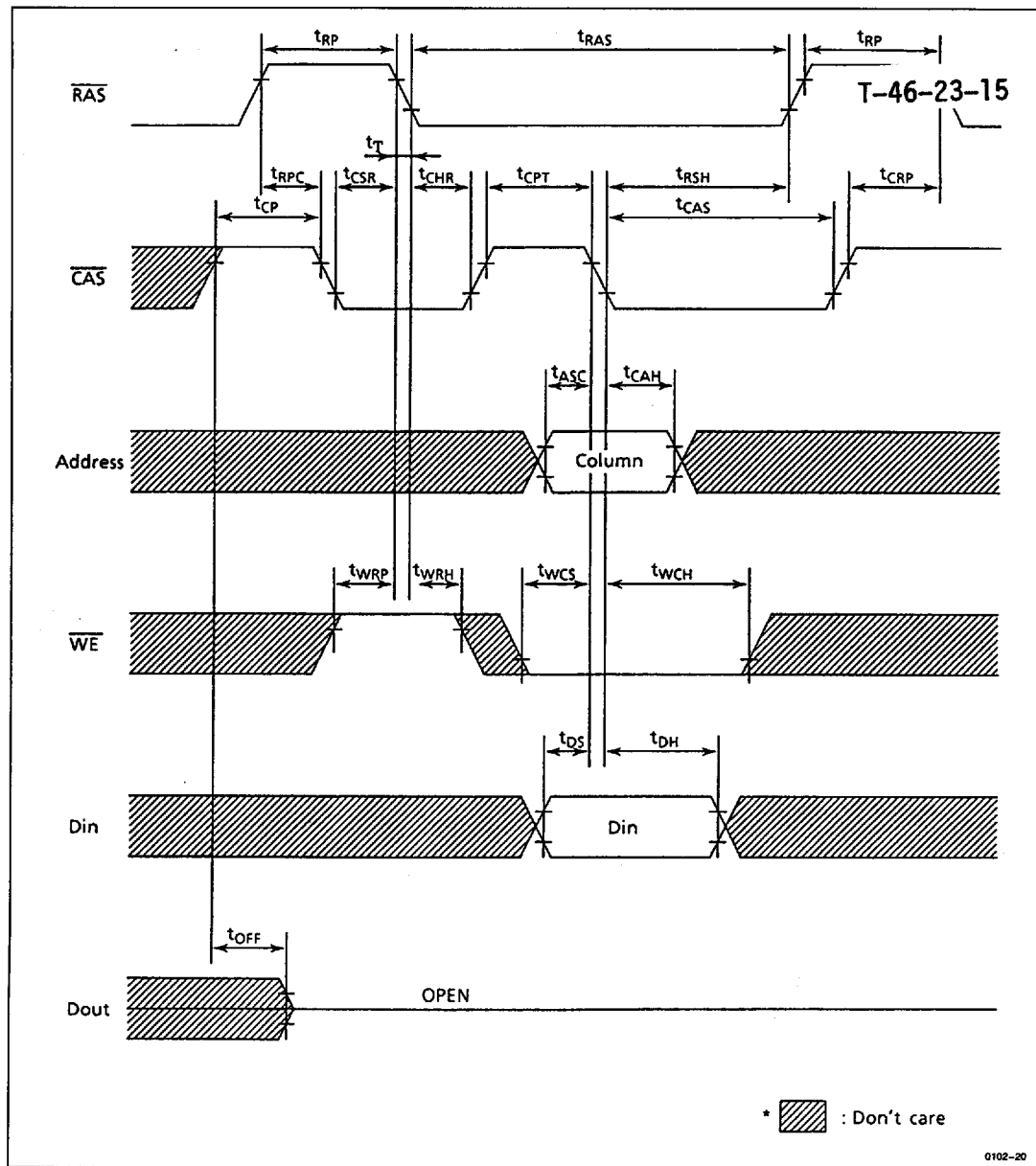
HITACHI/ LOGIC/ARRAYS/MEM

T-46-23-15



0102-19



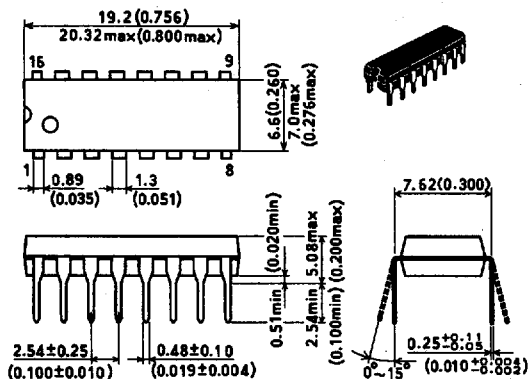


T-90-20

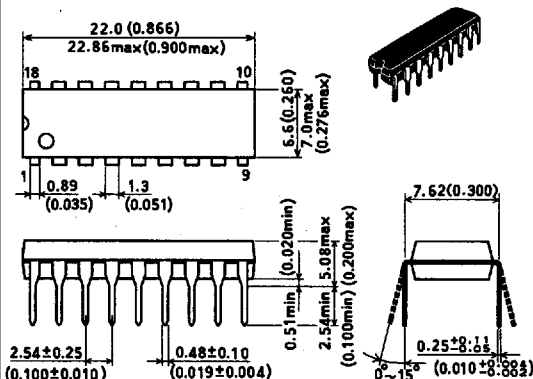
Unit: mm (inch) Scale 3/2

• Dual-in-line Plastic

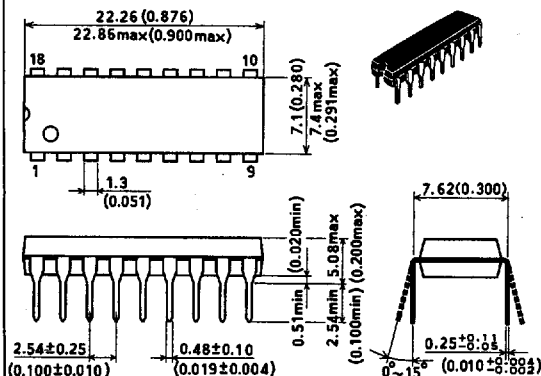
• DP-16B



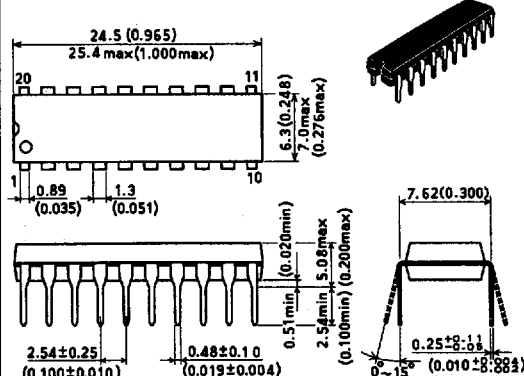
• DP-18B



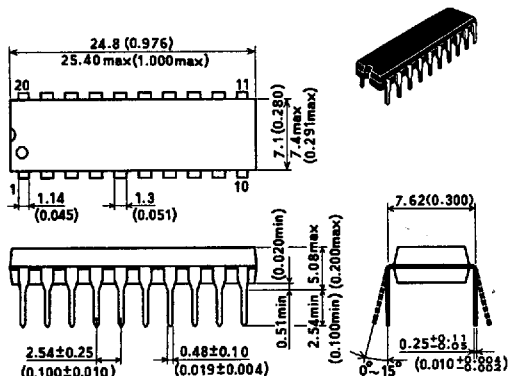
• DP-18C



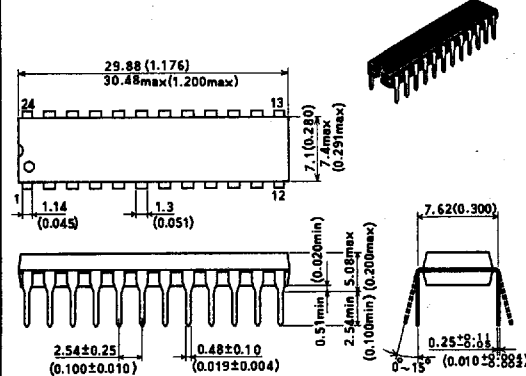
• DP-20N



• DP-20NA



• DP-20NC

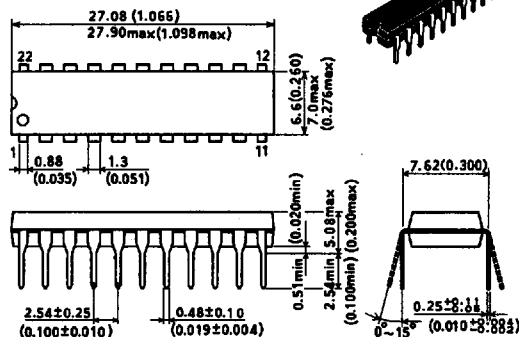


• Dual-In-line Plastic

HITACHI/ LOGIC/ARRAYS/MEM

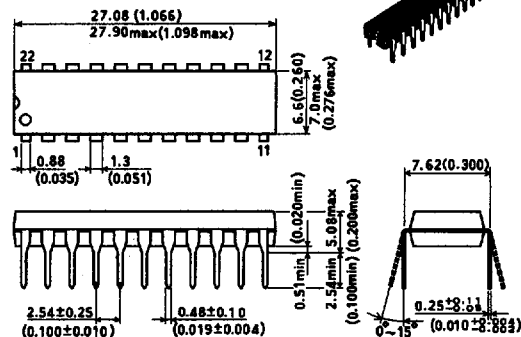
Unit: mm (inch) Scale 3/2

• DP-22N

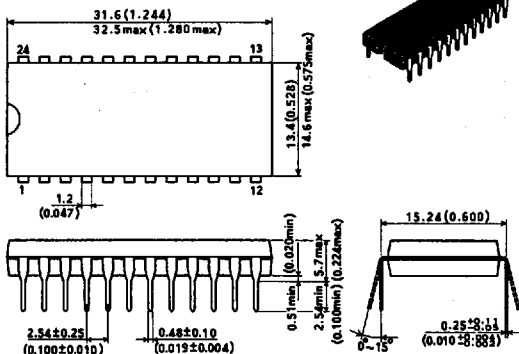


• DP-22NB

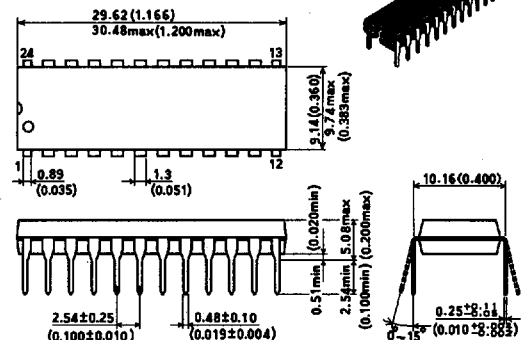
T-90-20



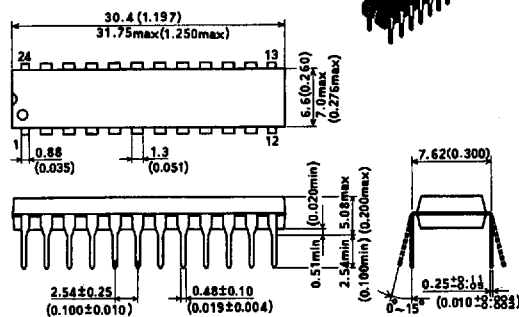
• DP-24



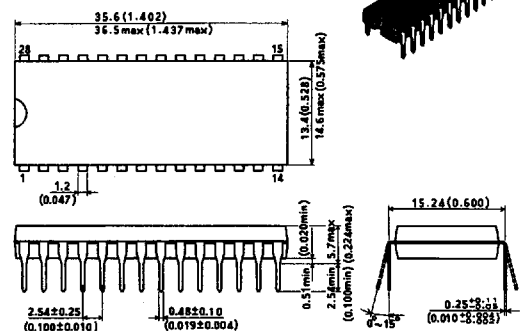
• DP-24A



• DP-24N



• DP-28

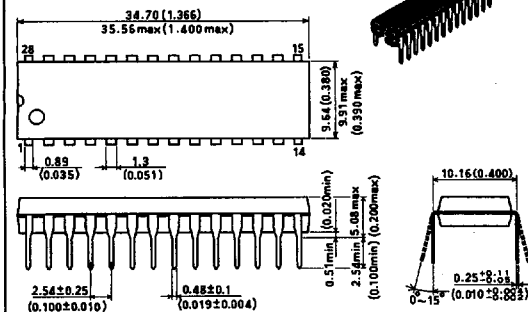


• Dual-in-line Plastic

HITACHI/ LOGIC/ARRAYS/MEM

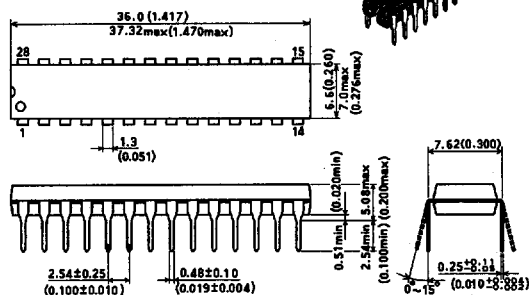
Unit: mm (inch) Scale 3/2

• DP-28C

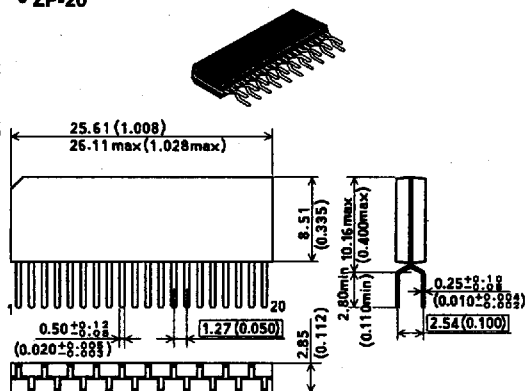


• DP-28N

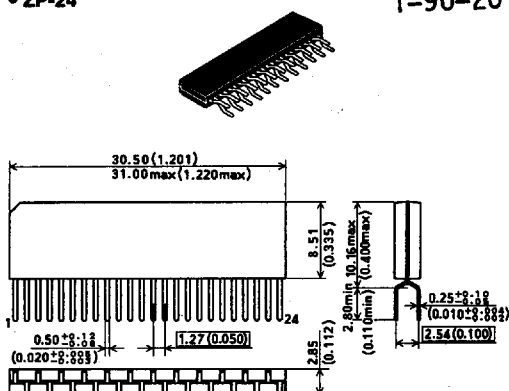
T-90-20



• ZP-20

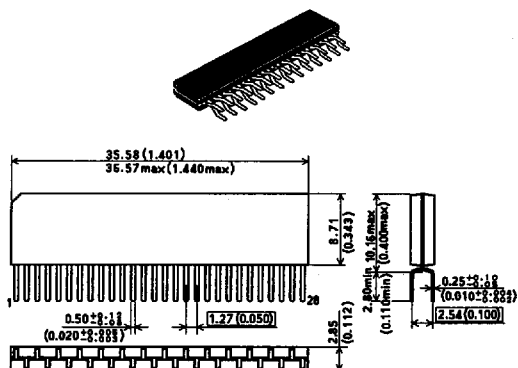


• ZP-24

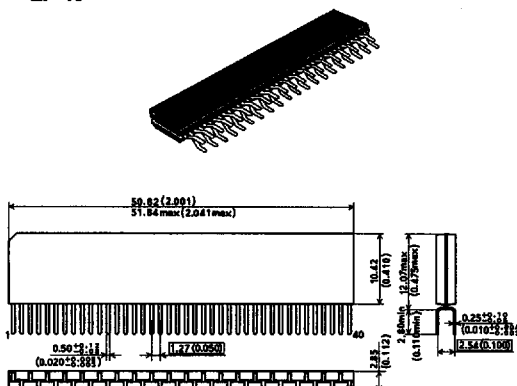


T-90-20

• ZP-28



• ZP-40



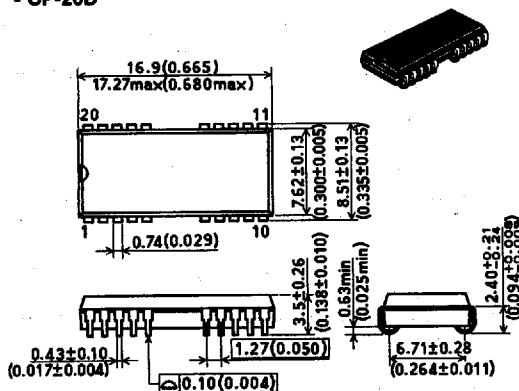
• Flat Package (J-bend Leads)

HITACHI/ LOGIC/ARRAYS/MEM

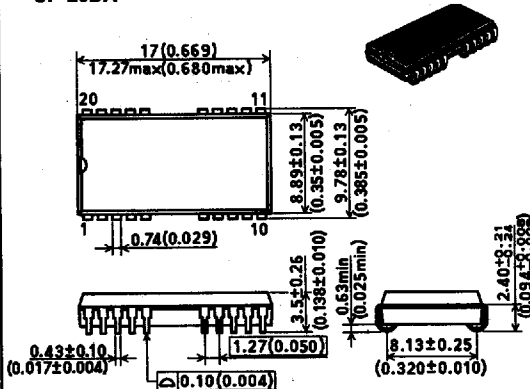
Unit: mm (inch) Scale 3/2

T-90-20

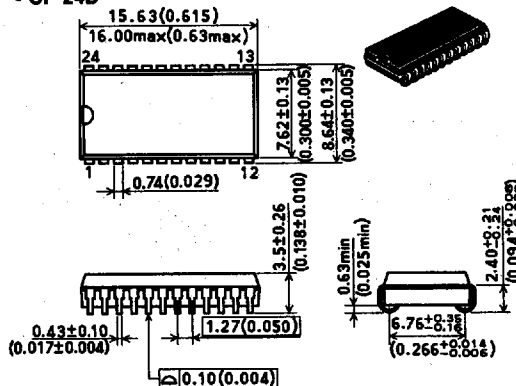
• CP-20D



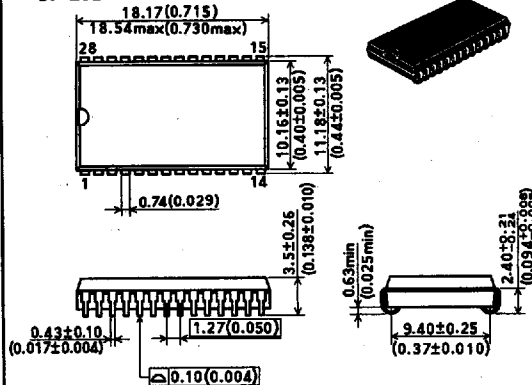
• CP-20DA



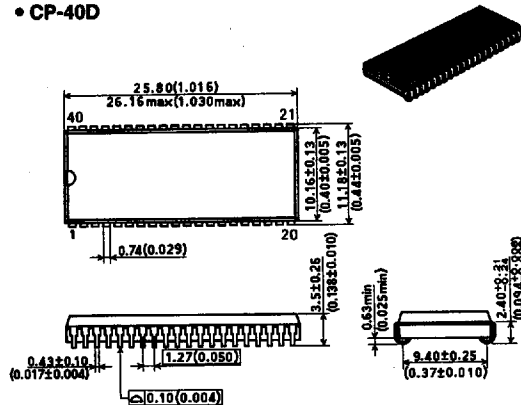
• CP-24D



• CP-28D



• CP-40D

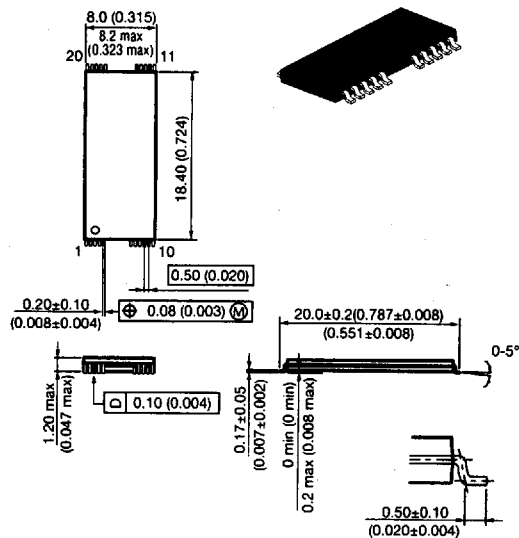


• TSOP (Thin Small Outline Package)

HITACHI/ LOGIC/ARRAYS/MEM

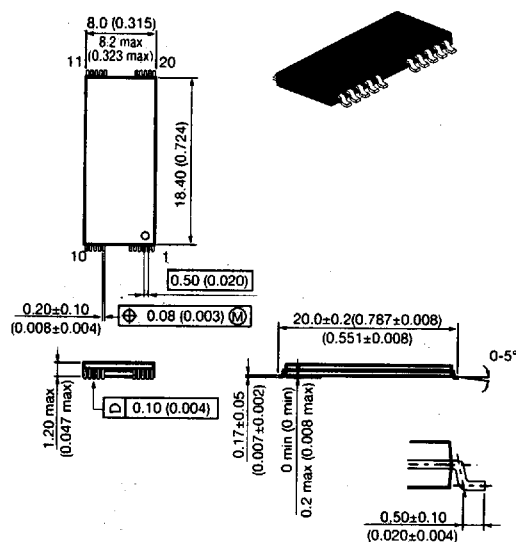
Unit: mm (inch) Scale 3/2

• TFP-20DA

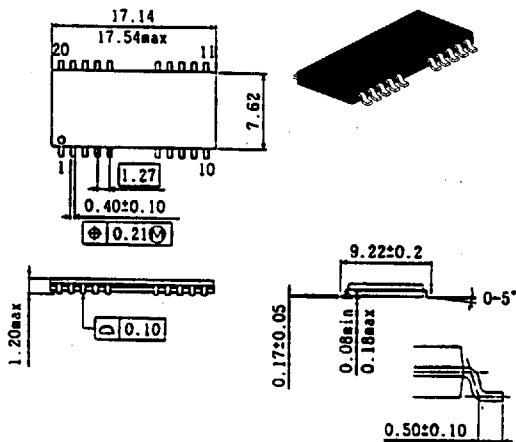


• TFP-20DAR

T-90-20



• TTP-20D



• TTP-20DR

